



## PCB BUILD SPECIFICATION FOR CNS12011V2

PCB Size (mm): XxY	25.5mm x 18mm	Thickness (mm): +/- 10%	1.0
Panel Size (mm): XxY	116.50mm x 94mm	Board Material:	FR4
PCBs per Panel:	9	Number of Layers:	2
Panelisation Details:	See electronic data 10mm Rail and PCB separation 4mm diameter non-plated tooling holes, 5mm from each corner 1mm diameter fiducials in 3 places on both sides with 2mm diameter resist relief.		

### Build Sequence from Top to Bottom

Description	Details	Thickness (µm)
Top Solder Mask	BLUE	n/a
Top Layer		18u + plating
FR4 Core		1000u
Bottom Layer		18u + plating
Bottom Solder Mask	BLUE	n/a

### Drill Information (per PCB)

	Number of sizes	Count
Layer – Top to Bottom	4	129
Total	4	129
Type of via holes:	Through (0.3mm)	

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CSR, Churchill House, Cambridge Business Park, Cowley Road, Cambridge, CB4 0WZ, UK.  
Tel: +44 (1223) 692000

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## Design Rules

	mm
Minimum Track Width	0.1
Minimum Track Gap	0.1
Minimum BGA Pad Diameter	
Minimum Hole Diameter (finished)	0.3
Minimum Annular Ring	0.15
Minimum Clearance on Solder Resist	0.05
Minimum Line width on Silkscreen	NA

## Finish

Immersion Tin	Immersion Ni Au	Hard Gold		Other
	Y			

## Specific Requirements

	Y/N	Comments
U.L Approval	Y	Bottom side Resist, away from tracks and pads
Date / Manufacturers code	N	
Half-plated holes	Y	
Plated slots	N	
Edge chamfer	N	
Peelable mask	N	
Impedance test required	N	

## Additional Information

Manufacture boards to BS EN 123000.  
Data must not be modified other than to allow for manufacturing process tolerances.  
VIA holes can be drilled at finished size if this aids copper annular ring  
Copper Balancing can be added to Panel frame if required (Do not copper balance the PCB).